

TSMC99-149B



Application No. 09/755,282

2822
5/Amndt B
P. Walker
3-12-02

February 8, 2002

TO: Commissioner of Patents and Trademarks
Washington, D.C. 20231

FROM: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/755,282
File Date: 01/08/01
Inventor: CHEN, SHENG-HSIUNG
Examiner: MITCHELL, JAMES
Art Unit: 2822
Title: METHOD OF IMPROVING COPPER PAD ADHESION

RESPONSE TO OFFICE ACTION

This is in response to the office action dated November 8, 2001. Please amend the above identified Divisional Application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on February 8, 2002.

Signature Stephen B. Ackerman Date: FEB. 8, 2002
Stephen B. Ackerman, Reg. No. 37,761